

Strained Silicon: Market Research Report

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Abstracts

This report analyzes the Global market for Strained Silicon in US\$ Million.

Annual forecasts are provided for the period 2006 through 2015.

The report profiles 66 companies including many key and niche players such as Advanced Micro Devices, Inc., Applied Materials, Inc., ASM International NV, Atmel Corporation, AmberWave Systems Corporation, Canon, Inc., CEVA, Inc., Chartered Semiconductor Manufacturing Ltd., Honeywell International, Inc., International Business Machines Corp., Isonics Corporation, Infineon Technologies, AG, Intel Corp., International Rectifier Corp., KLA Tencor Corporation, Maxim Integrated Products, Inc., MEMC Electronic Materials, Inc., Micron Technology Inc., Mitsubishi Materials Corporation, NEC Electronics Corporation, Oki Semiconductor Company Ltd., Peregrine Semiconductor Corp., Renesas Technology Corporation, Sandia National Laboratories, Soitec S. A., STMicroelectronics N.V., Shanghai Simgui Technology Co., Ltd, Shin-Etsu Handotai Co., Ltd., Silicon Genesis Corporation, Siltronic AG, Texas Instruments Incorporated, Toshiba Corporation, Taiwan Semiconductor Manufacturing Company Limited, United Microelectronic Corporation, and Vitesse Semiconductor Corporation.

Market data and analytics are derived from primary and secondary research.

Company profiles are mostly extracted from URL research and reported select online sources.

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AWR and austriamicrosystems Launch Process Design Kit for SiGe BiCMOS Process Technology
StrataLight Develops Silicon Germanium (SiGe) Chipset for 100GbE Transponders
Tokyo Instruments Develops Basic Technology for Non-Destructive Strain-Measuring Instrument
Silicon Genesis Unveils the First 20 mm Solar Cell Foils
Silicon Genesis Unveils the New PolyMax™ Process Technology
Fujitsu Unveils New Power-Saving CMOS Technology
UMC Announces the Launch of 65nm Customer Silicon, Using the Proprietary URAM Technology
Renesas Launches New Affordable Fabrication Technology
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Epson Commences Large-Scale Production of 0.7inch Full HD HTPS Panels
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Maxim Integrated Products Launches DS1091L Silicon EconOscillator™
Oki Electric Creates Extremely Low Cost-Effective μBOSA Chips for FTTH Modules
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AMG Invest Acquires Stakes in Graphit Kropfmuhl
Globe Specialty Metals Acquires Stakes in Solsil
Intrinsiq Materials Takes Over pSiNutria from pSiVida
Permatex Acquires Anaerobicos
AmberWave Acquires Aonex Technologies
IBM Adopts the QuickCap NX Parasitic Extraction Software from Magma
IMEC Selects SOI MEMS Technology From Tronics Microsystems
Silex System to Acquire Minority Stake in Translucent Photonics
LSI Corp Takes Over Tarari
E-Ton Solar Tech Takes Over ADEMA Technologies
Gintech and MEMC Completes Agreement for Solar Wafer Supply
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AmberWave Signs License Agreement with LG Siltron on Strained Silicon IP
ARM Acquires Soisic
Sumco to Takeover KEM
Samsung and Siltronic to Construct New Fab Facility
ARM Collaborates with Soitec (France)

5.FOCUS ON SELECT GLOBAL PLAYERS

Advanced Micro Devices, Inc. (USA)
Applied Materials, Inc. (USA)
ASM International NV (Netherlands)
Atmel Corporation (USA)
AmberWave Systems Corporation (USA)
Canon, Inc. (Japan)
CEVA, Inc. (USA)
Chartered Semiconductor Manufacturing Ltd (Singapore)
Honeywell International, Inc. (USA)
International Business Machines Corp. (USA)
Isonics Corporation (USA)
Infineon Technologies, AG (Germany)
Intel Corp. (USA)
International Rectifier Corp. (USA)
KLA Tencor Corporation (USA)

Maxim Integrated Products, Inc. (USA)
MEMC Electronic Materials, Inc. (USA)
Micron Technology Inc. (USA)
Mitsubishi Materials Corporation. (Japan)
NEC Electronics Corporation (Japan)
Oki Semiconductor Company Co. Ltd. (Japan)
Peregrine Semiconductor Corp. (USA)
Renesas Technology Corporation (Japan)
Sandia National Laboratories (USA)
Soitec S. A. (France)
STMicroelectronics N.V. (Switzerland)
Shanghai Simgui Technology Co., Ltd (China)
Shin-Etsu Handotai Co., Ltd (Japan)
Silicon Genesis Corporation (USA)
Siltronic AG (Germany)
Texas Instruments Incorporated (USA)
Toshiba Corporation (Japan)
Taiwan Semiconductor Manufacturing Company Limited (Taiwan)
United Microelectronic Corporation (Taiwan)
Vitesse Semiconductor Corporation (USA)

III. COMPETITIVE LANDSCAPE

Total Companies Profiled: 66 (including Divisions/Subsidiaries - 70)

Region/CountryPlayers

The United States

Japan

Europe

France

Germany

The United Kingdom

Rest of Europe

Asia-Pacific (Excluding Japan)

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